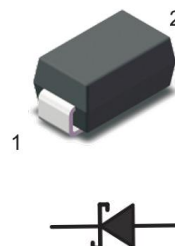


Features

- ◆ For surface mounted applications
- ◆ Metal silicon junction, majority carrier conduction
- ◆ Low power loss, high efficiency
- ◆ Built-in strain relief, ideal for automated placement
- ◆ High forward surge current capability
- ◆ Plastic package has underwriters laboratory flammability 94V-0
- ◆ Polarity: Color band denotes cathode end



Applications

- ◆ low voltage high frequency inverters
- ◆ Freewheeling
- ◆ Polarity protection applications

Dimensions (DO-214AC/SMA)

Symbol	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	1.250	1.650	0.049	0.065
B	3.990	4.550	0.157	0.178
C	2.540	2.790	0.100	0.110
D	1.980	2.290	0.078	0.090
E	0.780	1.550	0.030	0.061
F	-	0.203	-	0.008
G	4.75	5.280	0.194	0.208
H	0.152	0.305	0.006	0.012
I	1.800	-	0.070	-
J	2.100	-	0.082	-
K	-	2.300	-	0.090

Maximum Ratings ($T_A=25^{\circ}\text{C}$ unless otherwise specified)

Parameter	Symbol	SS							Unit
		22A	23A	24A	26A	28A	210A	220A	
Repetitive peak reverse voltage	V _{RRM}	20	30	40	60	80	100	200	V
Maximum RMS Voltage	V _{RMS}	14	21	28	42	56	70	140	V
Maximum DC Blocking Voltage	V _{DC}	20	30	40	60	80	100	200	V
Maximum Average Forward Current	I _{F(AV)}	2.0							A
Peak Forward Surge Current,8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I _{FSM}	50							A
Maximum instantaneous forward voltage @2A	V _F	0.55		0.70	0.85			0.95	V
Maximum DC reverse current at rated DC blocking voltage per diode @ V _{RM} =V _{RRM}	I _R @25℃	0.5			0.3				mA
	I _R @100℃	5			3				
Typical Junction Capacitance (Note1)	C _J	220		80					pF
Thermal resistance(Note2)	Rθ _{J-A}	80							℃/W
Junction temperature	T _j	-55~+125							℃
Storage temperature	T _{stg}	-55 ~+150							℃

Notes: 1. Measured at 1 MHz and applied reverse voltage of 4 V D.C
2. P.C.B. mounted with 2.0" X 2.0" (5 X 5 cm) copper pad areas.

Ratings and Characteristic Curves ($T_A=25^\circ\text{C}$ unless otherwise noted)

Figure 1. Forward Current Derating Curve

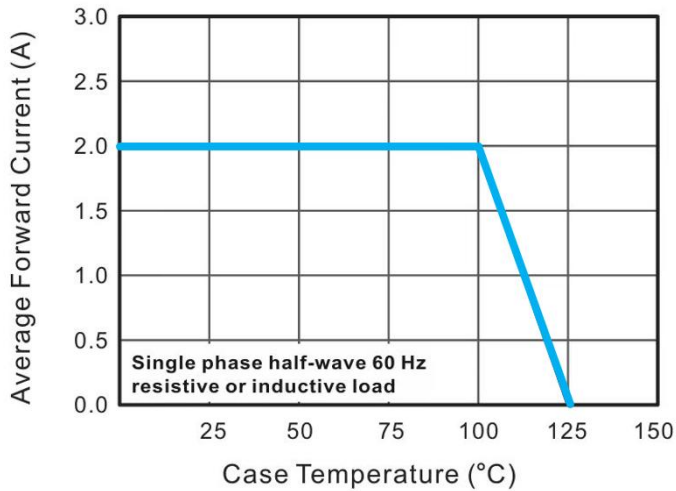


Figure 2. Typical Reverse Characteristics

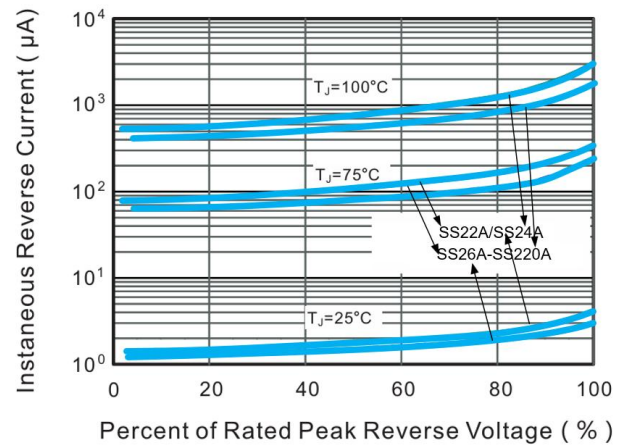


Figure 3. Typical Forward Characteristic

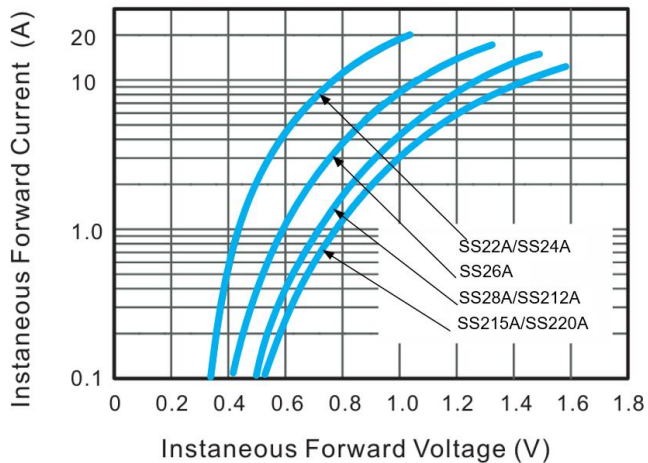


Figure 4. Typical Junction Capacitance

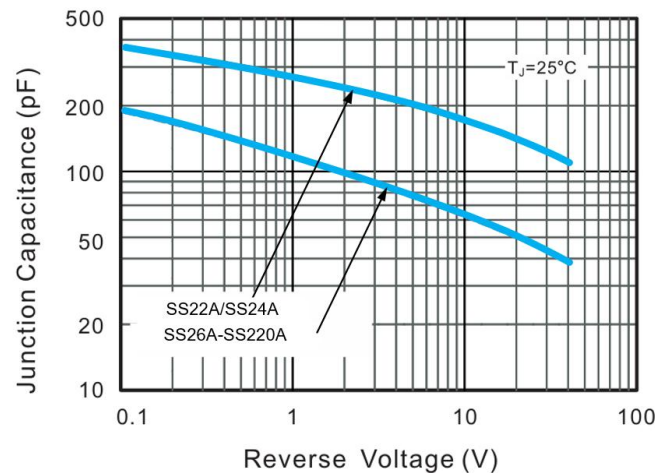


Figure 5. Maximum Non-Repetitive Peak Forward Surge Current

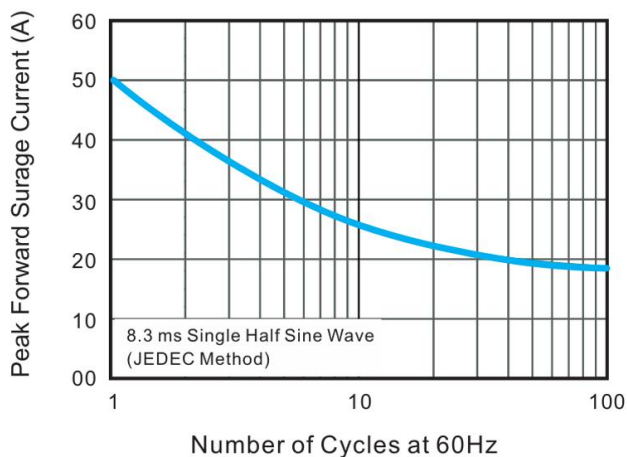
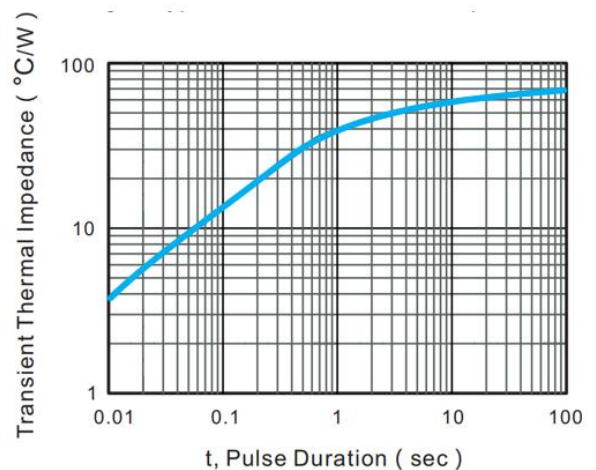
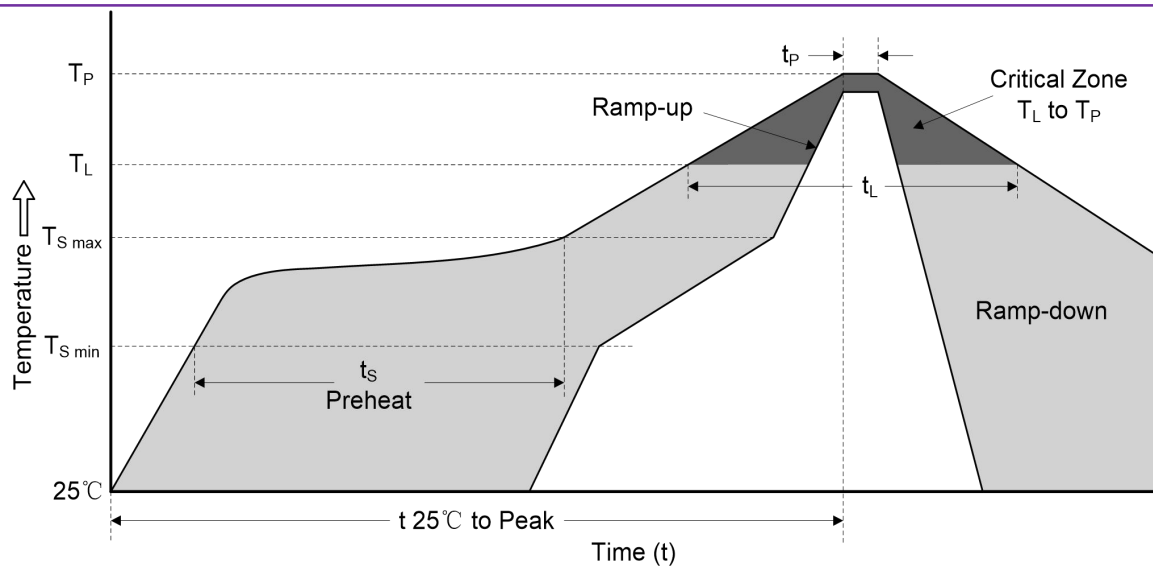


Figure 6. Typical Transient Thermal Impedance



Reflow Soldering Parameters



Reflow Condition		Lead-free Assembly
Pre heat	-Temperature Min ($T_{S\ min}$)	150°C
	-Temperature Max ($T_{S\ max}$)	200°C
	-Time (min to max) (t_s)	60-180 seconds
Average ramp-up rate (T_L to T_P)		3°C/second max.
$T_{S\ max}$ to T_L -Ramp-up Rate		3°C/second max.
Reflow	-Temperature (T_L) (Liquidus)	217°C
	-Time (min to max) (t_s)	60-150 seconds
Peak Temperature (T_P)		260(+0/-5)°C
Time within 5°C of actual Peak Temperature (t_p)		20-40 seconds
Ramp-down Rate		6°C/second max.
Time 25°C to Peak Temperature(T_P)		8 minutes max.
Do not exceed		260°C